

REMARKS/ARGUMENTS

The Examiner is thanked for the thorough examination and search of the subject.

5

Claims 219-223, 228, 232, 236, 238-242, 250-257, 259, 260 and 262-267 are pending; Claims 219-223, 228, 232, 236, 238-242, 250-257, 260, 262, 263 and 265-267 have been currently amended; Claims 1-218, 224-227, 229-231, 233-235, 237, 243-249, 258 and 261 have been canceled. No new matter is believed to have been added.

10

Response to Claim Rejections under 35 U.S.C. 102 and 103

Applicants respectfully traverse the rejections for at least the reasons set forth below.

15

Response to Claims 219-223, 228-236, 238-242, 250-257, 259, 260 and 262-267

=====

20 ==

As currently amended, independent claim 219 is recited below:

219. A chip package comprising:

a substrate;

only one die having a first top surface at a horizontal level;

25

an adhesive material joining said substrate and said only one die;

a first insulating layer over said horizontal level, over said only one die, over said substrate and across an edge of said only one die, wherein said first insulating layer comprises a first portion over said only one die and a second portion over said substrate but not over said only one die;

a patterned circuit layer over said first insulating layer, over said horizontal level, over said only one die and over said substrate, wherein said patterned circuit layer is connected to said only one die through a first opening in said first insulating layer;

5 an inductor over said horizontal level and over said first insulating layer;
and
a second insulating layer on said inductor.

=====

==

10

Section I:

Reconsiderations of Claims 219-223, 228, 232, 236, 238, 239, 250, 251, 257, 259, 260 and 263-267 rejected under 35 U.S.C. 103(a) as being unpatentable over Tabrizi (U.S. Pat. No. 6,867,499) in view of Ahn et al. (U.S. Pub. No. 2003/0020180),
15 *of Claim 240 rejected under 35 U.S.C. 103(a) as being unpatentable over Tabrizi in view of Ahn et al., further in view of Tahara et al. (U.S. Pub. No. 2002/0017730), of Claim 241 rejected under 35 U.S.C. 103(a) as being unpatentable over Tabrizi in view of Ahn et al., further in view of Jun et al. (U.S. Pub. No. 2002/0084510), of Claims 252-256 rejected under 35 U.S.C. 103(a) as being unpatentable over Tabrizi*
20 *in view of Ahn et al., further in view of Korman (U.S. Pat. No. 5,959,357), of Claim 262 rejected under 35 U.S.C. 103(a) as being unpatentable over Tabrizi in view of Ahn et al., further in view of Alcoe et al. (U.S. Pub. No. 2002/0135063) are requested based on the following remarks.*

25 Applicants respectfully assert that the chip package claimed in Claim 219 patentably distinguishes over the citations by Tabrizi (U.S. Pat. No. 6,867,499) in view of Ahn et al. (U.S. Pub. No. 2003/0020180).

Tabrizi teaches that “passive elements such as resistors, capacitors, and

inductors may be added on a redistribution layer or on the additional dielectric layers to provide a higher-level integrated electronic component.” ~ See col. 5, lines 1-4 ~ In accordance with Tabrizi’s teaching, those skilled in the art could understand that after a redistribution layer 22 and a dielectric layer 25 are formed, an inductor could
5 be mounted over the redistribution layer 22 and over the dielectric layer 25. ~ See Fig. 1 ~ In the case, after the inductor is mounted, those skilled in the art would consider that no insulating layer should be formed on the inductor because Tabrizi teaches that there is no insulating layer formed on an inductor. It is believed that the claimed subject matter of an insulating layer on an inductor can not be obvious over
10 Tabrizi’s teaching in view of Ahn et al.’s teaching.

Withdrawal of Rejection under 35 U.S.C. 103(a) to Claim 219 is respectfully requested.

15 For at least the foregoing reasons, applicants respectfully submit independent Claim 219 patently distinguishes over the prior art references, and should be allowed. For at least the same reasons, dependent Claims 220-223, 228-236, 238-242, 250-257, 259, 260 and 262-267 patently define over the prior art as well.

20 **Section II**

Reconsiderations of Claims 219, 236, 238, 239, 257, 259, 264 and 266 rejected under 35 U.S.C. 103(a) as being unpatentable over Saia et al. (U.S. Pat. No. 5,874,770) in view of Tabrizi (U.S. Pat. No. 6,867,499) are requested based on the following remarks.

25

Applicants respectfully assert that the chip package claimed in Claim 219 patentably distinguishes over the citations by Saia et al. (U.S. Pat. No. 5,874,70) in view of Tabrizi (U.S. Pat. No. 6,867,499).

The Examiner considers that "It would have been obvious to one of ordinary skill in the art to attach the die of Saia with the substrate of Tabrizi in order to provide an alternative means to package the chip of Saia as taught by Tabrizi." ~ See point 34 on page 9, in the last Office Action mailed Feb. 27, 2008 ~

5

Applicants respectfully traverse the Examiner's opinion because it would have not been obvious to one of ordinary skill in the art to attach the die of Saia with the substrate of Tabrizi. Saia et al.'s substrate 45 is formed by a molding process. ~ See Fig. 10 and col. 7, lines 24-38 ~ Tabrizi's substrate 10 is a silicon wafer. ~ See Fig. 1 and col. 2, lines 13-16 ~ It is believed that Tabrizi's substrate 10 is non-analogous to Saia et al.'s substrate 45 because Tabrizi's substrate 10, silicon wafer, can not be formed by a molding process as used to form Saia et al.'s substrate 45. Furthermore, Saia et al.'s substrate 45 is joined with a die 44 not using an adhesive material as used to join Tabrizi's substrate 10 with a die 12. Saia et al.'s substrate 45 has significantly different characteristics from those Tabrizi's substrate 10, and therefore Tabrizi's substrate 10 is non-analogous to Saia et al.'s substrate 45.

15

Withdrawal of Rejection under 35 U.S.C. 103(a) to Claim 219 is respectfully requested.

20

For at least the foregoing reasons, applicants respectfully submit independent Claim 219 patently distinguishes over the prior art references, and should be allowed. For at least the same reasons, dependent Claims 220-223, 228-236, 238-242, 250-257, 259, 260 and 262-267 patently define over the prior art as well.

25

Conclusion

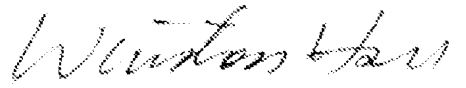
Some or all of the pending claims are believed to be in condition for Allowance, and that is so requested. Applicant respectfully requests that a timely Notice of

Appl. No. 10/055,568
Reply to Office action of February 27, 2008

Allowance be issued in this case. Applicant respectfully requests that a timely Notice of Allowance be issued in this case.

Sincerely yours,

5



Date: 06.27.2008

Winston Hsu, Patent Agent No. 41,526

P.O. BOX 506, Merrifield, VA 22116, U.S.A.

Voice Mail: 302-729-1562

10 Facsimile: 806-498-6673

e-mail : winstonhsu@naipo.com

Note: Please leave a message in my voice mail if you need to talk to me. (The time in D.C. is 12 hours behind the Taiwan time, i.e. 9 AM in D.C. = 9 PM in Taiwan.)

15